

## Special Issue

# BIM and HBIM: Standardisation and interoperability

### Message from the Guest Editors

This Special Issue of the journal *Applied Sciences*, “BIM and HBIM, Standardization and Interoperability” will outline how the proposed solutions for interoperability and the use of standards can bring advantages for BIM and HBIM applications (including design and construction projects, use of BIM in urban space planning, historical built heritage documentation, conservation projects, and asset management, together with the projects that address the emerging problems of our era: lower energy consumptions, smart networking, logistics, guide to choices and strategies for conservation, enhancing resilience, and so on).

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### Guest Editors

Dr. Antonia Spano  
Dr. Francesca Noardo  
Dr. Margarita Kokla

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### Deadline for manuscript submissions

closed (30 January 2020)



## Applied Sciences

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## About the Journal

### Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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### Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo  
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